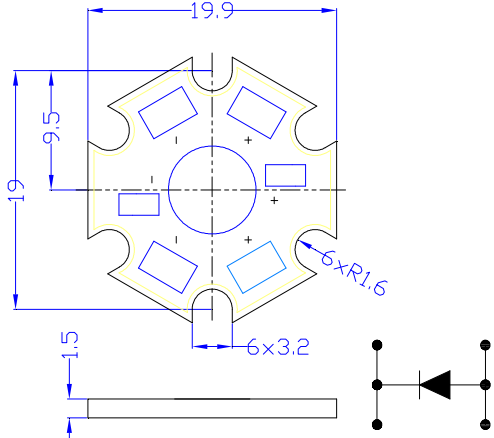

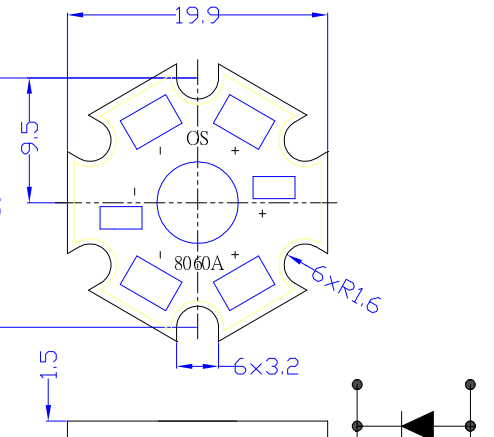



Heat Sink for Xeon Series					
Item	Part Number	Description	Dimension	Photo	Application
1W	OSMCPCB8060B	<ul style="list-style-type: none"> Aluminum metal-base copper-clad laminate PCB Design for Xeon 1 Power Series LED Base metal is 1.5mm Aluminum With NTCD Thermally Conductive Dielectric Copper Circuit Foil is 35 μ m(1oz) Surface Finish is Black Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	 <p>Unit:mm Tolerance:±0.30mm</p>		Used for Xeon 1 Power Series, eg: OSW4XME1C1E
3W	OSMCPCB8060A	<ul style="list-style-type: none"> Aluminum metal-base copper-clad laminate PCB Design for Xeon 3 Power Series LED Base metal is 1.5mm Aluminum With HTCD Thermally Conductive Dielectric to suitable high power LED Copper Circuit Foil is 35 μ m(1oz) Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant) 	 <p>Unit:mm Tolerance:±0.30mm</p>		Used for Xeon 3 Power Series, eg: OSW4XME1C1E

Appendix

Data and information for MCPCB

<u>Items</u>	<u>Unit</u>	<u>Reference</u>
Thermal Conductivity	W/mK	0.8W/mK
Dielectric thickness	μ m	100
Breakdown voltage	kV(DC)	> 3kV
Insulation resistance	Ω	10^5
Maximum Working Temperature	$^{\circ}$ C	130
Peel Strength	N/mm	> 1.4
Blistering after heat shock within 1 minutes	$^{\circ}$ C	<260
Copper thickness	μ m	35
Base metal plate	-	Aluminum
Base metal thickness	mm	1.5